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Declarations under Rule 4.17:

- as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii))
- as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii))

[Continued on next page]

(54) Title: LIFT-OFF DEPOSITION SYSTEM FEATURING A DENSITY OPTIMIZED HULA SUBSTRATE HOLDER IN A CONICAL DEPOSITION CHAMBER

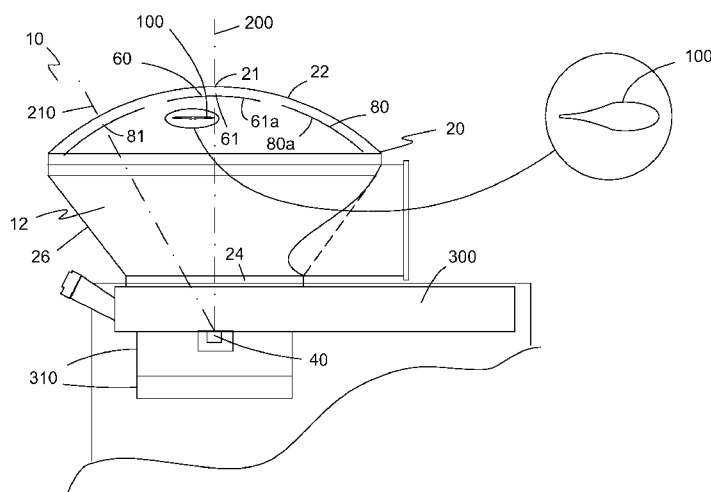


Fig. 1

(57) Abstract: A vapor deposition device using a lift-off process includes an evaporation source, a space frame mounted for rotation about a first axis that passes through the evaporation source, a central dome-shaped wafer holder mounted to the space frame wherein a centerpoint of the central dome-shaped wafer holder is aligned with the first axis, an orbital dome-shaped wafer holder mounted to the space frame in a position offset from the first axis and rotatable about a second axis that passes through a centerpoint of the orbital dome-shaped wafer holder and the evaporation source, and a plurality of wafer positions on the central dome-shaped wafer holder and the orbital dome-shaped wafer holder where each of the wafer positions are offset from the first axis and the second axis. Each of the plurality of wafer positions are configured to orient a substrate surface of a wafer mounted therein substantially orthogonal to a radial axis extending from the wafer position to the evaporation source during rotation about the first axis and the second axis.

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